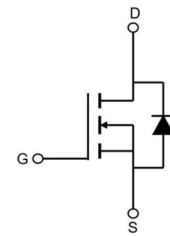


# AP40N100LK

## N-Channel Enhancement Mosfet

### Feature

- 100V,25A  
 $R_{DS(ON)} < 25m\Omega @ V_{GS}=10V$  (TYP:19.5m $\Omega$ )  
 $R_{DS(ON)} < 33\Omega @ V_{GS}=4.5V$  (TYP:27.5 m $\Omega$ )
- Split Gate Trench Technology
- Lead free product is acquired
- Excellent  $R_{DS(ON)}$  and Low Gate Charge



Schematic Diagram



Marking and pin assignment

### Application

- PWM applications
- Load Switch
- Power management

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
40N100LK	AP40N100LK	TO-252	13 Inch	-	2500

### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_a = 25^\circ\text{C}$ )	$I_D$	25	A
Continuous Drain Current ( $T_a = 100^\circ\text{C}$ )	$I_D$	18	A
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	100	A
Single Pulsed Avalanche Energy <sup>(2)</sup>	$E_{AS}$	16	mJ
Power Dissipation	$P_D$	45	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.5	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

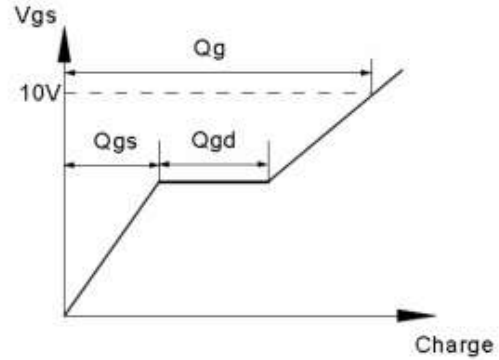
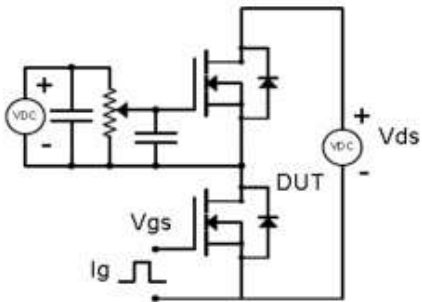
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	100	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage <sup>(3)</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.6	1.2	2.0	V
Drain-source on-resistance <sup>(3)</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	-	19.5	25	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	27.5	33	mΩ
Forward Threshold Voltage	g <sub>fs</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	-	22	-	S
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =V <sub>GS</sub> =0V, f =1MHz	-	1.52	-	Ω
<b>Dynamic characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f =1MHz	-	822	-	pF
Output Capacitance	C <sub>oss</sub>		-	310	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	23.5	-	
<b>Switching characteristics</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	15	-	ns
Turn-on rise time	t <sub>r</sub>		-	3.2	-	
Turn-off delay time	t <sub>d(off)</sub>		-	30	-	
Turn-off fall time	t <sub>f</sub>		-	7.6	-	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	22.7	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	6.2	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	5.3	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		59		nC
Reverse Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		45		ns
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(3)</sup>	V <sub>DS</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =10A	-	-	1.2	V
Diode Forward current <sup>(4)</sup>	I <sub>S</sub>		-	-	25	A

**Notes:**

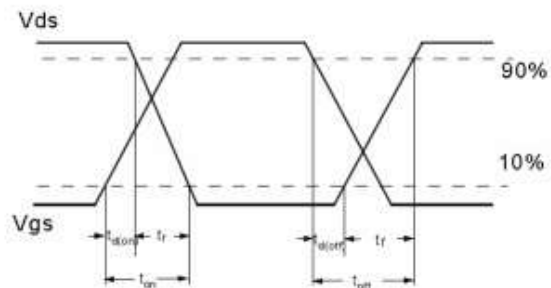
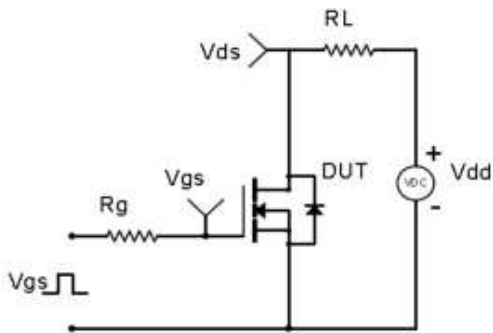
1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, R<sub>G</sub>=25 Ω, L=0.5Mh
3. Pulse Test: pulse width≤300μs, duty cycle≤2%
4. Surface Mounted on FR4 Board, t≤10 sec

**Test Circuit & Waveform**

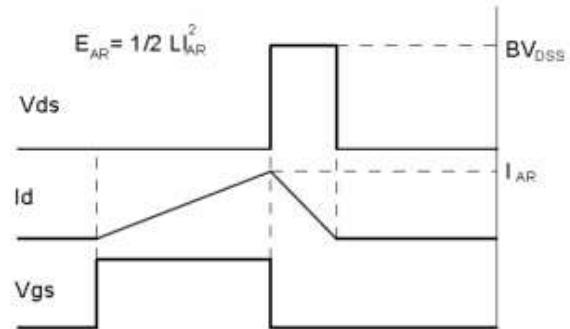
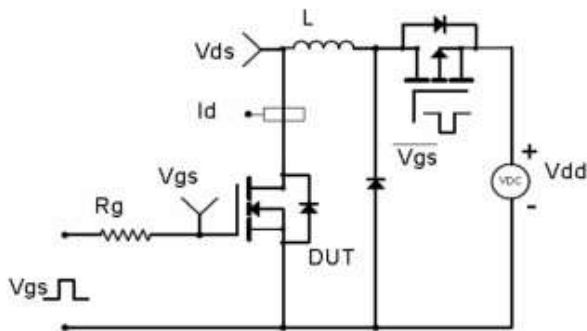
Gate Charge Test Circuit & Waveform



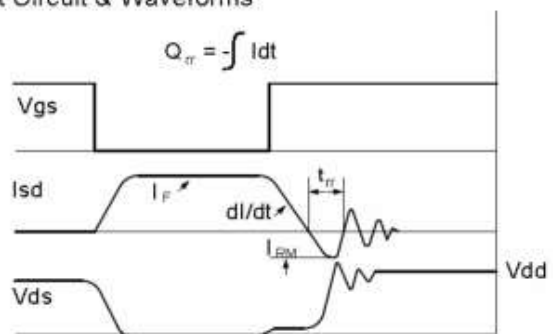
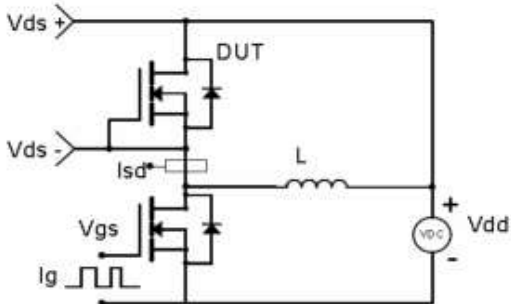
Resistive Switching Test Circuit & Waveforms



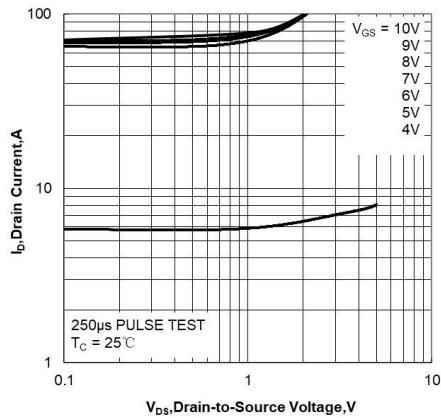
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



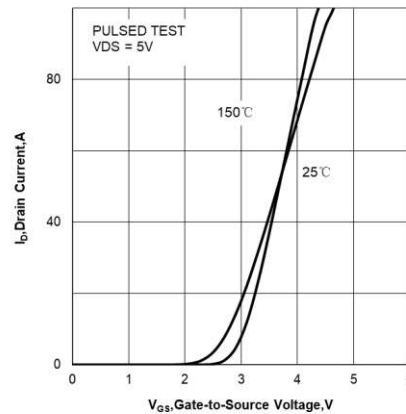
Diode Recovery Test Circuit & Waveforms



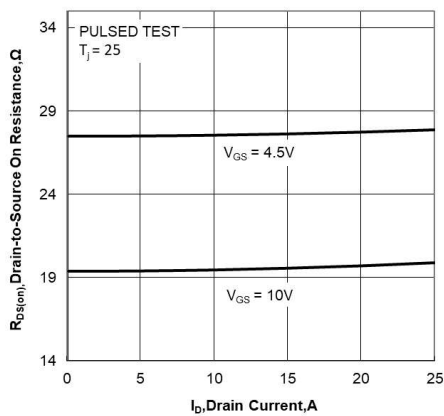
**Typical Performance Characteristics**



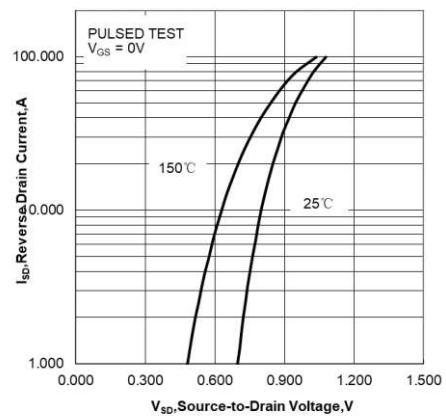
**Figure 1. Output Characteristics**



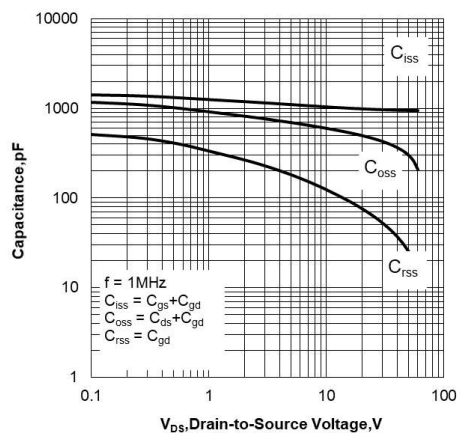
**Figure 2. Transfer Characteristics**



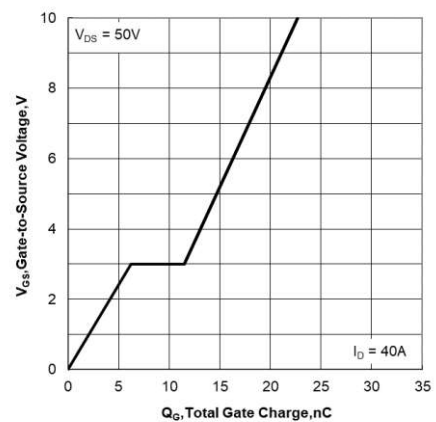
**Figure 3. Drain-to-Source On Resistance vs Drain Current**



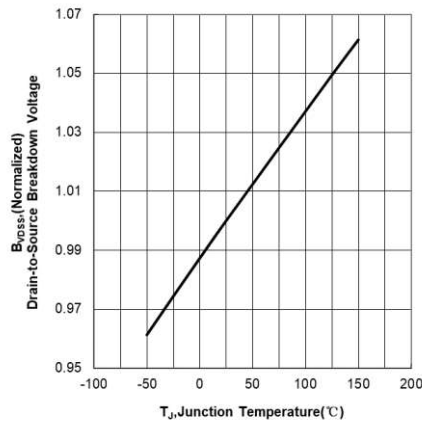
**Figure 4. Body Diode Forward Voltage vs Source Current and Temperature**



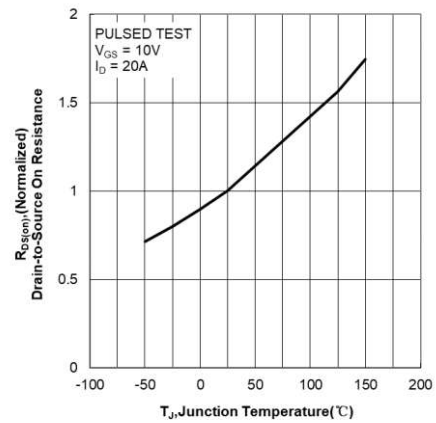
**Figure 5. Capacitance Characteristics**



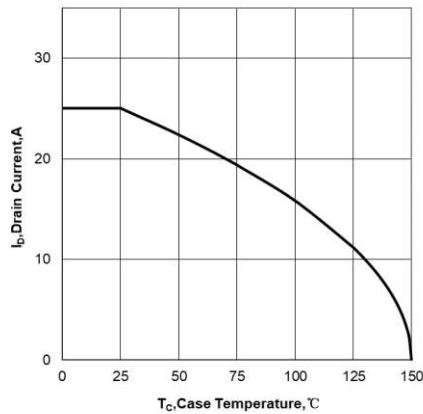
**Figure 6. Gate Charge Characteristics**



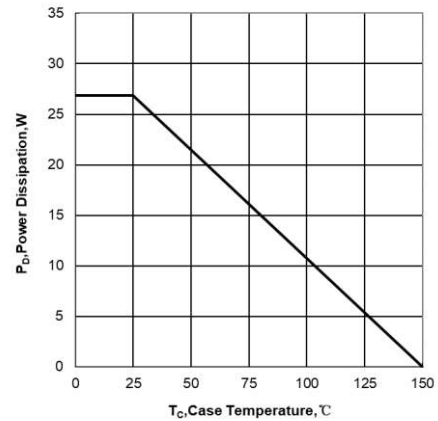
**Figure 7. Normalized Breakdown Voltage vs Junction Temperature**



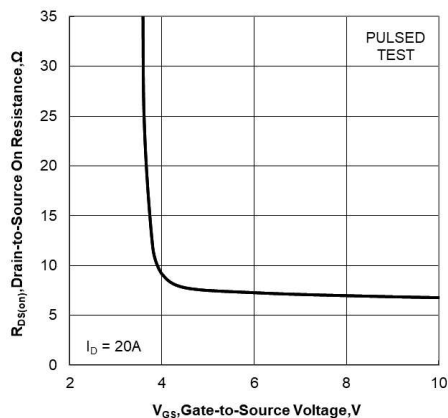
**Figure 8. Normalized On Resistance vs Junction Temperature**



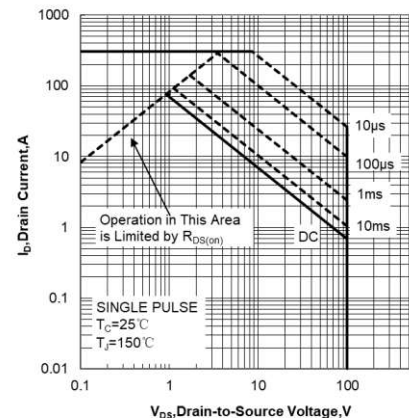
**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



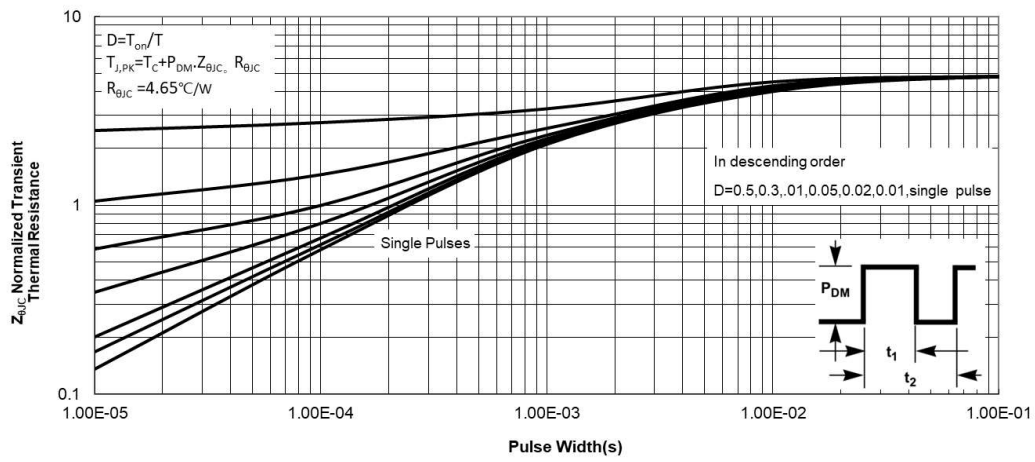
**Figure 10. Maximum Power Dissipation vs Case Temperature**



**Figure 11. Drain-to-Source On Resistance vs Gate Voltage and Drain Current**

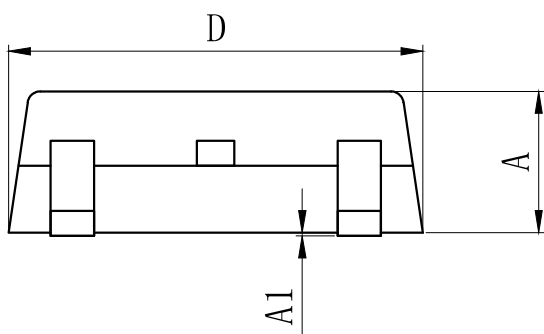
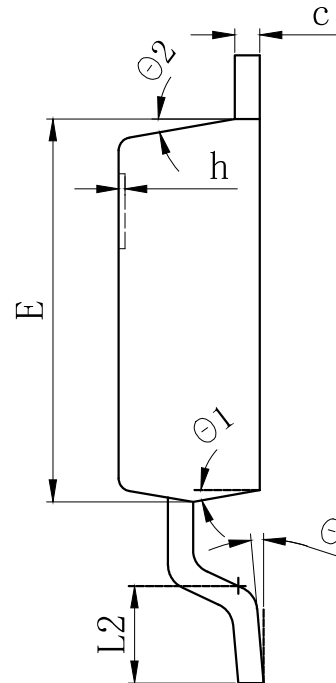
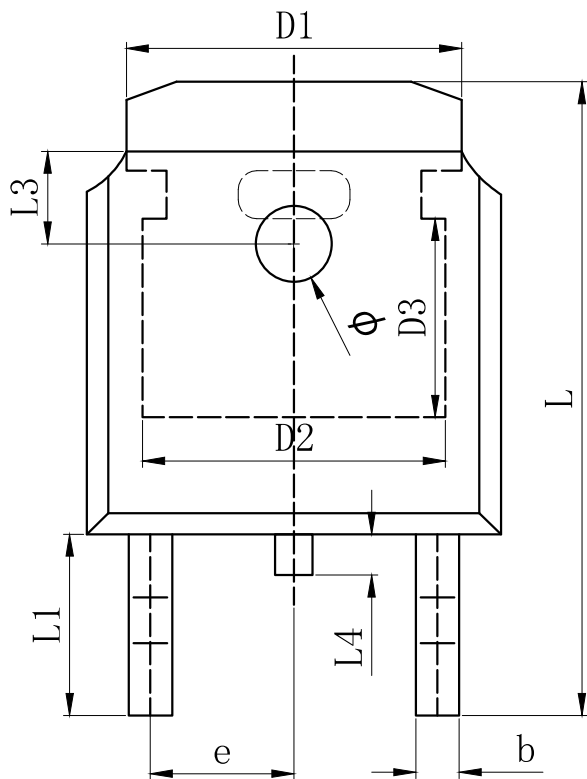


**Figure 12. Maximum Safe Operating Area**



**Figure 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**TO-252 Package Information**



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
$\Phi$	1.100	1.200	1.300
$\theta$	0°		8°
$\theta_1$	9° TYP		
$\theta_2$	9° TYP		